



520.40395X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: SUGIURA et al.  
Serial No.: 09/930,944  
Filed: August 17, 2001  
For: ELECTRONIC DEVICE SEALING ELECTRONIC  
ELEMENT THEREIN AND MANUFACTURING METHOD  
THEREOF, AND PRINTED WIRING BOARD  
Group: 2831  
Examiner: H. Ngo

#10 / *[Signature]*  
D. EVANS  
9.12.02

SUPPLEMENTAL AMENDMENT

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

September 6, 2002

Sir:

In supplement to the Amendment filed on September 3, 2002, please further  
amend the above-identified as follows:

In the Specification:

Page 1, paragraph beginning at line 7 and continuing to page 2, has been  
rewritten as indicated below:

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The present invention relates to an electronic device, in which an electronic  
element is hermetically sealed, and a method for manufacturing thereof, and further  
a printed wiring board being suitable for use in such an electronic device.

B1  
Conventionally, an electronic element, such as a SAW (Surface Acoustic  
Wave) element, etc., is hermetically sealed within an electronic part case, for the  
purpose of protecting the property or characteristics of the SAW element from being